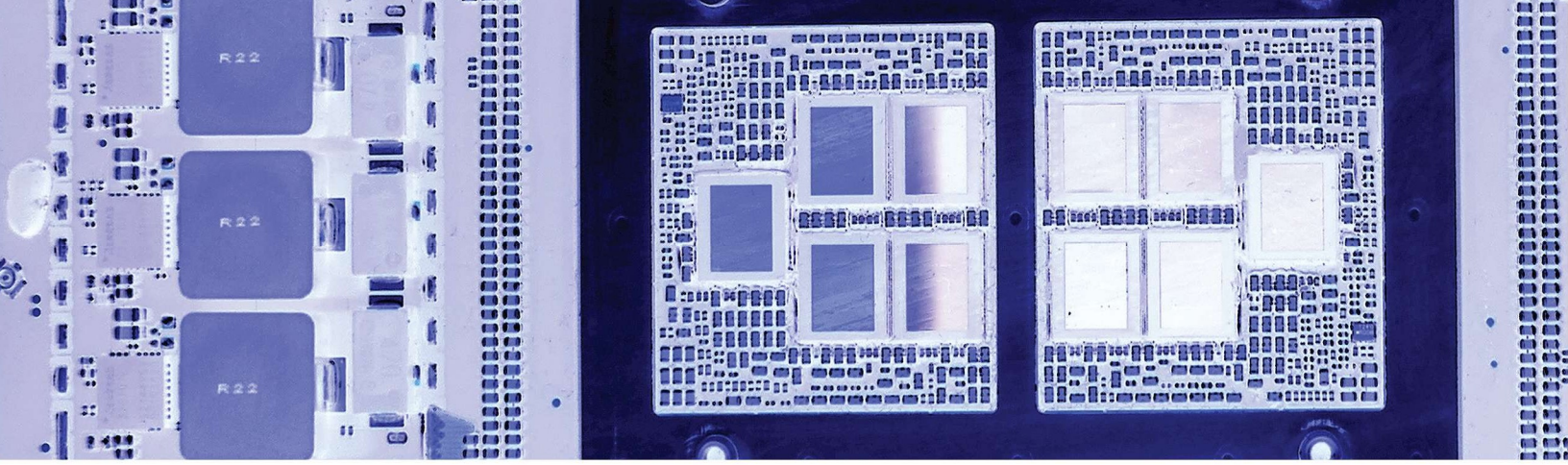

THE SEMICONDUCTOR AND PACKAGING REPORT

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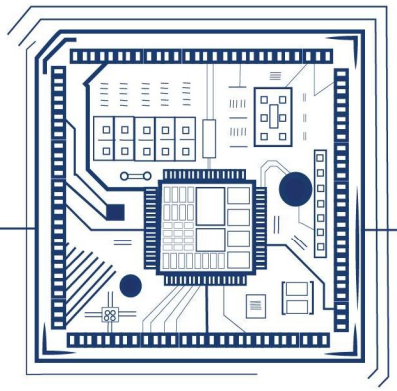
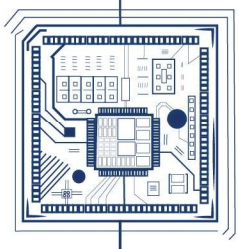


Second Quarter 2026

- **State of the Semiconductor and Package Business**
  - Prismark's global economic and electronics outlook for 2025/2026F/2030F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- **2025 and 2026 Semiconductor Market Overview and 2030 Forecast**
  - Review of semiconductor market performance in 2025, outlook for 2026, and five-year forecasts covering end-market demand, semiconductor devices, package types, and packaging value-add trends.
- **IC Packaging and Assembly Market: Updated View For 2025–2026 and 2030 Outlook**
  - Revised wire bond and flip chip unit forecasts to 2030, a restructured CoWoS-S/R/L classification framework for high-density packages, and updated IC assembly value projections.
- **Semiconductor Back-End Equipment Market**
  - How advanced packaging equipment diverges from mature assembly toolsets, the four growth vectors driving capacity additions, the vendor landscape across front-end incumbents and back-end specialists, and lead times now constraining AI hardware output.
- **Updates on Chinese CPU/GPU and AI Chip Design Companies**
  - 1H 2026 results for China's fabless CPU, GPU, and AI accelerator designers, covering revenue and profitability, R&D intensity, and new product introductions
- **Company News: Semiconductor and Wafer Fabrication**
  - Updates on leading semiconductor and foundry companies, including major business developments, strategic initiatives, technology advancements, and new product introduction.
- **Company News: Semiconductor Packaging**
  - Recent developments in packaging at leading OSAT and captive assembly operations.



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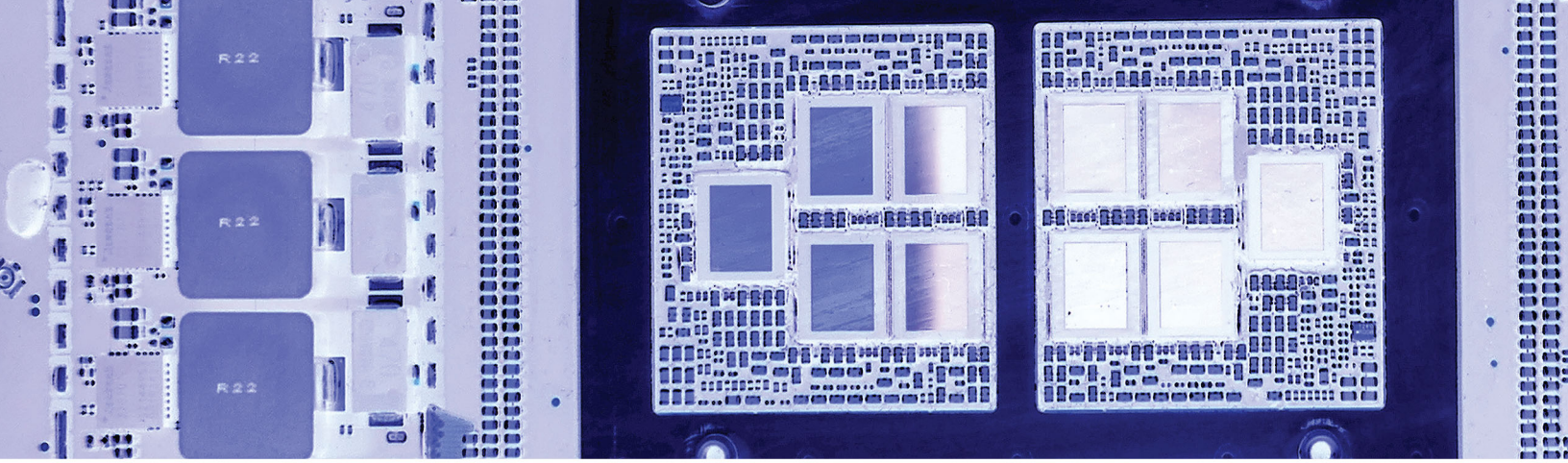

THE SEMICONDUCTOR AND PACKAGING REPORT

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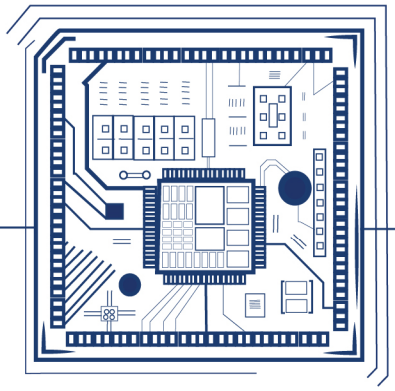
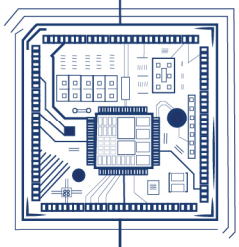


First Quarter 2026

- **State of the Semiconductor and Package Business**
  - Prismark's global economic and electronics outlook for 2025/2026F/2030F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- **2025, 2026 Semiconductor Market Overview and 2030 Forecast**
  - Review of semiconductor market performance in 2025, outlook for 2026, and five-year forecasts covering end-market demand, semiconductor devices, package types, and packaging value-add trends.
- **Update on the AI Accelerator and Related Advanced Packaging Market**
  - Updated assessment of the AI accelerator market, including shipment and revenue outlooks, key demand drivers, and the resulting impact on advanced packaging capacity requirements.
- **Substrate Market and Material Shortages**
  - Review of the substrate market, key drivers behind current material shortages, and Prismark's forecast for glass fabric manufacturing capacity based on announced expansion plans from major suppliers.
- **Advanced Packaging Update in PCs**
  - Overview of advanced packaging technologies adopted in leading PC SoCs
- **Huawei Tao Law and Explain its Correlation with Advanced Packaging**
- **Updates on China's 12-Inch Wafer Fabrication Developments**
- **Company News: Semiconductor and Wafer Fabrication**
  - Updates on leading semiconductor and foundry companies, including major business developments, strategic initiatives, technology advancements, and new product introduction.
- **Company News: Semiconductor Packaging**
  - Recent developments in packaging at leading OSAT and captive assembly operations.



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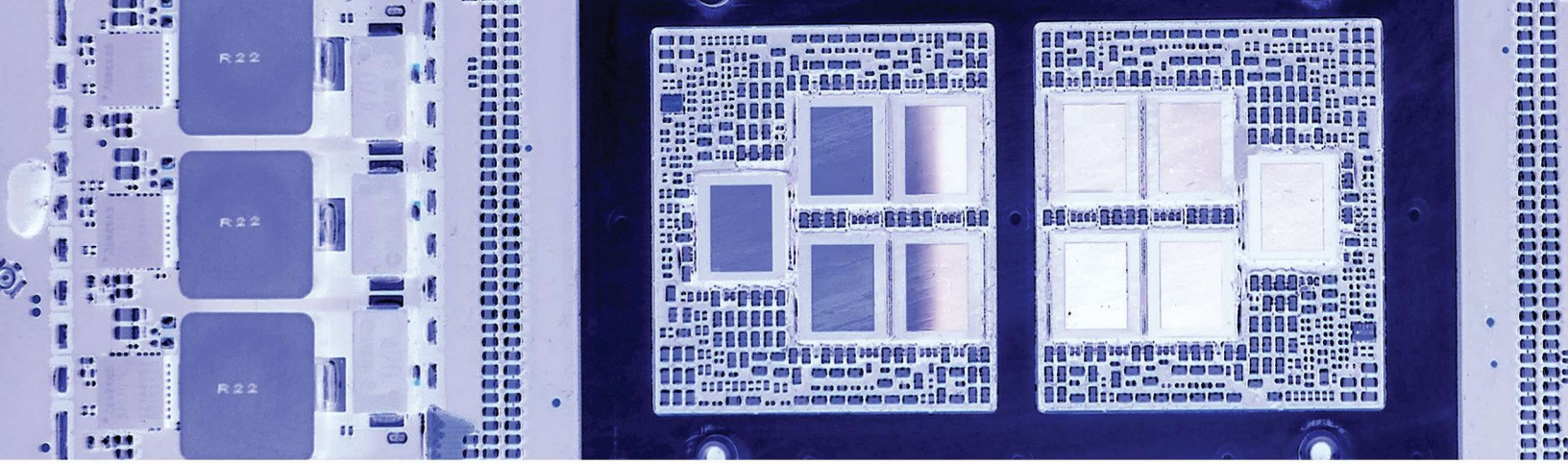

THE SEMICONDUCTOR AND PACKAGING REPORT

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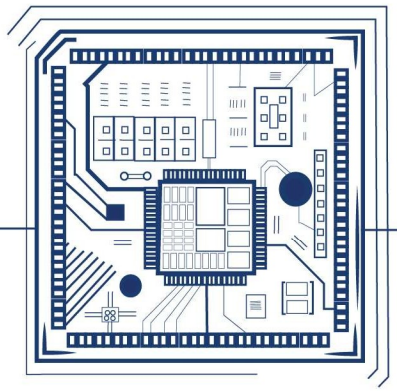
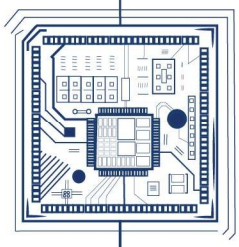


FOURTH QUARTER • 2025

- **State of the Semiconductor and Package Business**
  - Prismark's global economic and electronics outlook for 2025/2026F/2030F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- **2025, 2026 Semiconductor Market Overview and 2030 Forecast**
  - Review of the semiconductor market in 2025, with forecasts for 2026 and five-year forecasts for end market, device, package type, and packaging value-add are provided.
- **Update on the AI Accelerator and Related Advanced Packaging Market**
  - This chapter reviews AI accelerator demand and its impact on advanced packaging technologies such as CoWoS and HBM, along with hyperscaler data-center investment trends and packaging capacity constraints.
- **Memory Technology and Market Trends for AI Data Centers**
  - This chapter reviews memory technologies and market trends in AI data centers, focusing on the evolution of HBM and its packaging technologies. It also examines emerging memory architectures such as HBF, CXL, PIM, and ZAM that could expand or reshape the AI memory hierarchy.
- **Updates on Taiwanese NB and Server ODMs**
  - Updates on key notebook and server ODMs and their recent business performance and investment activities.
- **Company News: Semiconductor and Wafer Fabrication**
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- **Company News: Semiconductor Packaging**
  - Recent developments in packaging at leading OSAT and captive assembly operations.



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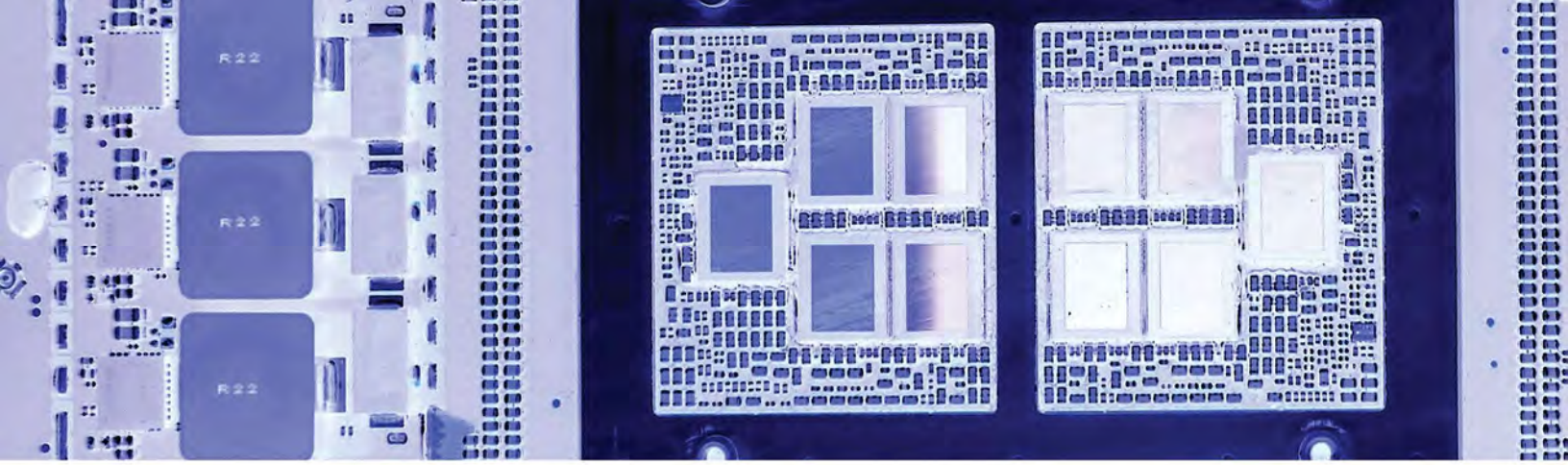

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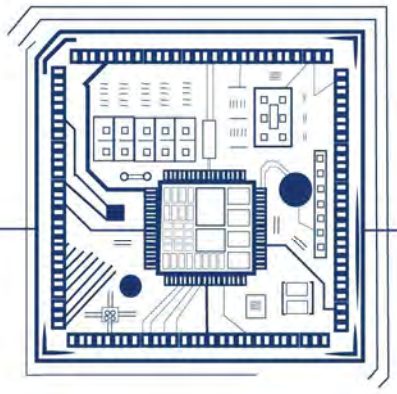
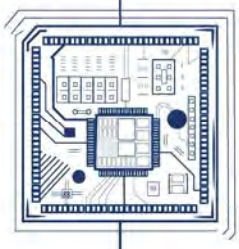


FIRST QUARTER • 2025

- State of the Semiconductor and Package Business
  - Prismark's global economic and electronics outlook for 2025, and actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- 2025 Semiconductor Market Outlook and 2029 Forecast
  - Outlook for the semiconductor market in 2025, with five-year forecasts for end market, device, package type, and packaging value-add are provided
- Co-Packaged Optics in Data Centers
  - Recent developments in photonics integration and packaging have enabled the commercialization of high-performance network switches and deployment of Co-Packaged Optics in data center applications. Continuing bandwidth escalation needs will also likely expand CPO adoption beyond networking switch ASICs into XPU interconnects and other applications
- Updates on China's 12-Inch Wafer Fabrication Developments
  - Updates, recent business performance, and investment activities in China's 12-inch wafer fabrication sector
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations



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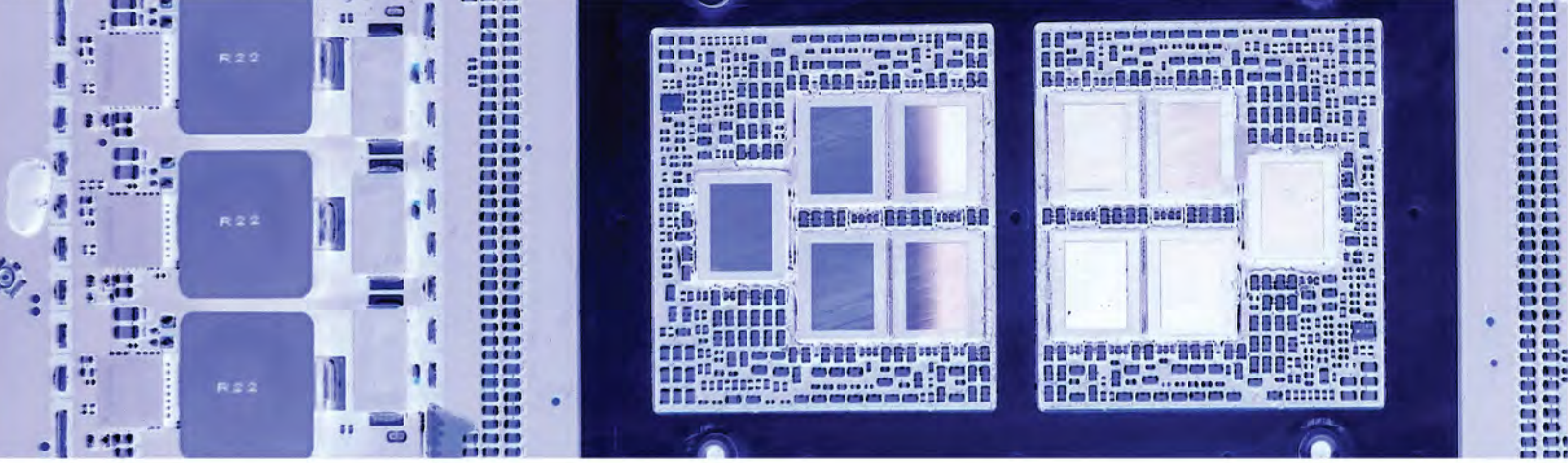

THE SEMICONDUCTOR AND PACKAGING REPORT

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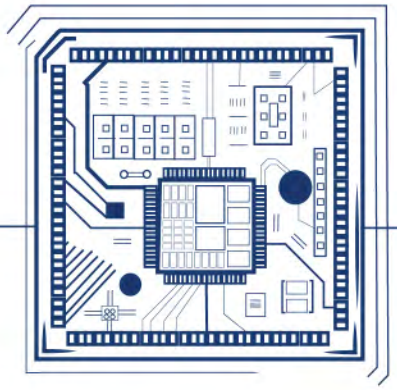
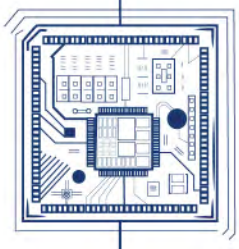


April 2025 • Fourth Quarter 2024

- State of the Semiconductor and Package Business
  - Prismark's global economic and electronics outlook for 2024/2025F/2029F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- 2024 Semiconductor Market Review and 2025 and 2029 Forecasts
  - Review of the semiconductor market in 2024, with forecasts for 2025 and five-year forecasts for end market, device, package type, and packaging value-add are provided
- Power Module Packaging
  - Power module usage has increased tremendously in the past decade due to the EV transition, railway transport, and green power investments. Power module assembly was historically the principal business of large IDMs. In this section, we discuss assembly technologies and market dynamics and trends
- Updates on Advanced Packaging in PCs
  - Advanced packaging has escalated over the past several decades. Although the focus has now shifted to AI accelerators at data centers, the state-of-the-art packaging technologies will gradually penetrate the personal electronics market to enable AI on the edge. In this section, we share some recent teardown analyses of PC SoCs and peripherals, and our updated view on the advanced packaging market
- Updates on Taiwanese NB and Server ODMs
  - Updates on key notebook and server ODMs and their recent business performance and investment activities
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations



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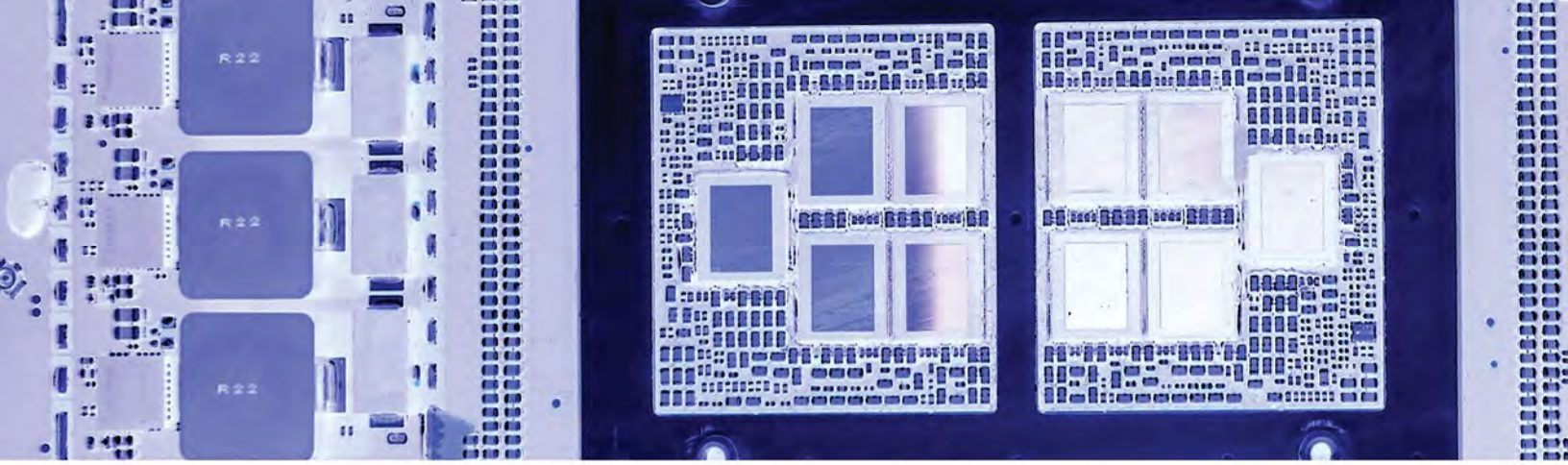

THE SEMICONDUCTOR AND PACKAGING REPORT

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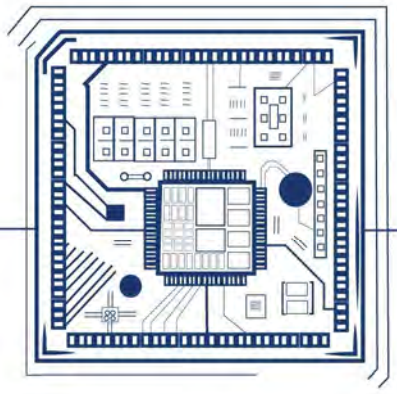
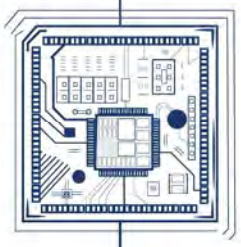


December 2024 • Third Quarter 2024

- State of the Semiconductor and Package Business
  - Prismark's global economic and electronics forecast for 2023/2024F/2028F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- 2024 Semiconductor Market Review, Preliminary 2025 and 2028 Forecast
  - Updated forecasts for 2024, preliminary 2025 and five-year forecasts by end market, device, package type, and packaging value-add are provided
- Evolution of the Chinese Semiconductor Supply Chain and Outlook
  - Geopolitics has accelerated the development of a self-sustaining Chinese semiconductor supply chain, leading towards a bifurcated industry. This has significant implications for all levels of the electronics industry from materials to finished systems. A review of the leading Chinese players within the Foundry, Fabless, OSAT, and Tool supplier sectors along with commentary about global and regional semiconductor subsidy trends
- Updates on the Handset Market and Local Smartphone Suppliers in China
  - Handset market and smartphone local suppliers in China developments
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations



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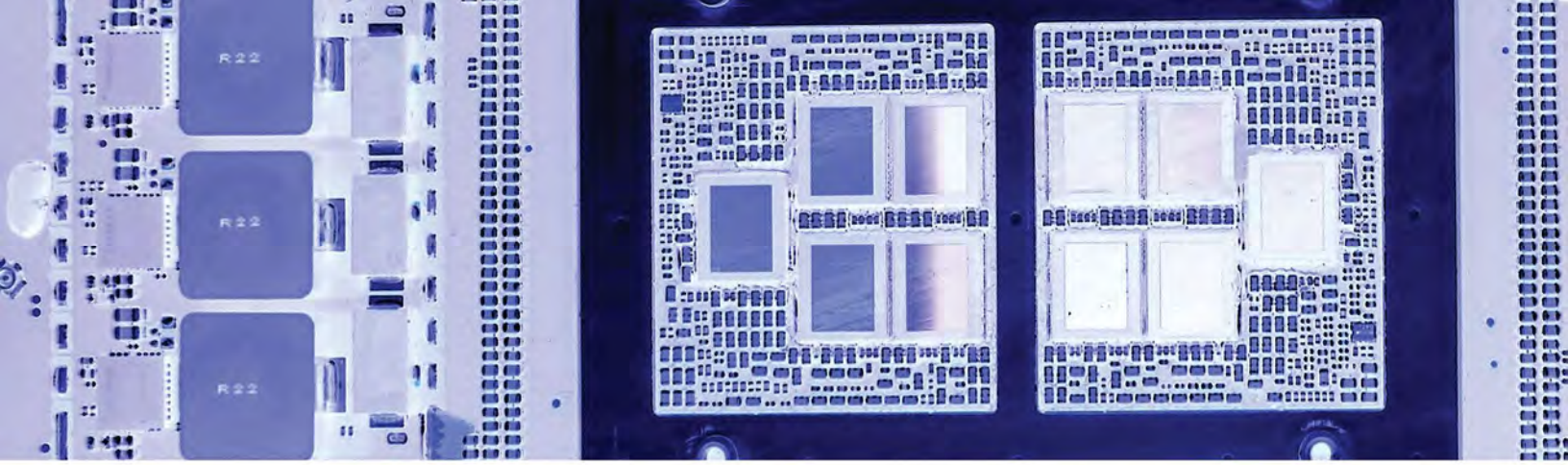

THE SEMICONDUCTOR AND PACKAGING REPORT

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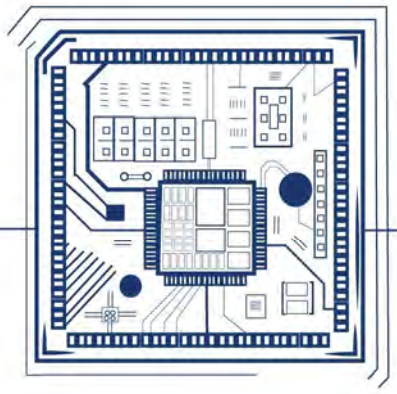
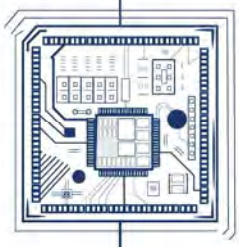


October 2024 • Second Quarter 2024

- State of the Semiconductor and Package Business
  - Prismark's global economic and electronics forecast for 2023/2024F/2028F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- 2024 Semiconductor Market Review and 2028 Forecast
  - Updated forecasts for 2024 and five-year forecasts by end market, device, package type, and packaging value-add are provided
- Recent Developments in Advanced Packaging
  - Discussion and highlights from recent teardowns regarding use of advanced packaging for PC, smartphone, server, and automotive applications. There is no one solution that serves all masters equally, and the supply chain is evolving to build out adequate capacity to address each application in a logical way
- Updates on Taiwanese Server ODMs
  - Updates on Taiwanese Server ODM developments
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations



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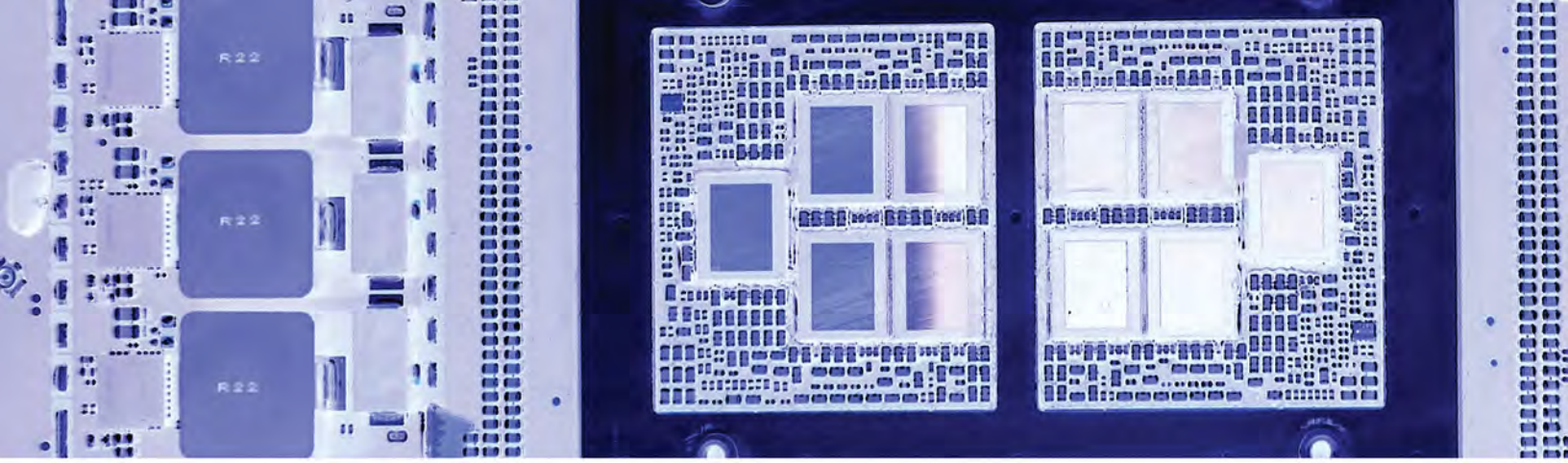

THE SEMICONDUCTOR AND PACKAGING REPORT

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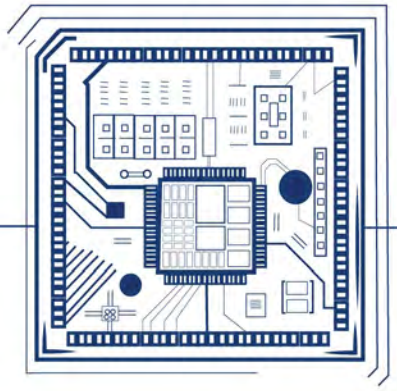


FIRST QUARTER • 2024

- State of the Semiconductor and Package Business
  - Prismark's global economic and electronics forecast for 2023/2024F/2028F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries

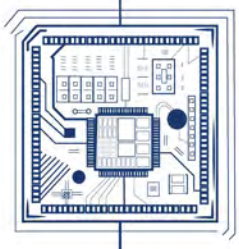
- 2024 Semiconductor Market Review and 2028 Forecast
  - Review of semiconductor market and package trends for 2024 and an outlook to 2028. Detailed unit and value forecasts by device type and package type, highlighting the increasing importance of advanced packaging to overall packaging value-add

- Semiconductor Manufacturing Investment and Equipment Market: Wafer Fab Overcapacity?
  - Review of semiconductor capex trends and likelihood of overcapacity resulting from the combination of lingering pandemic supply chain expansion, technology investments and geopolitically driven subsidies

- Updates on China's 12-Inch Wafer Fabrication Developments
  - Updates on China's wafer fabrication production developments

- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings

- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations



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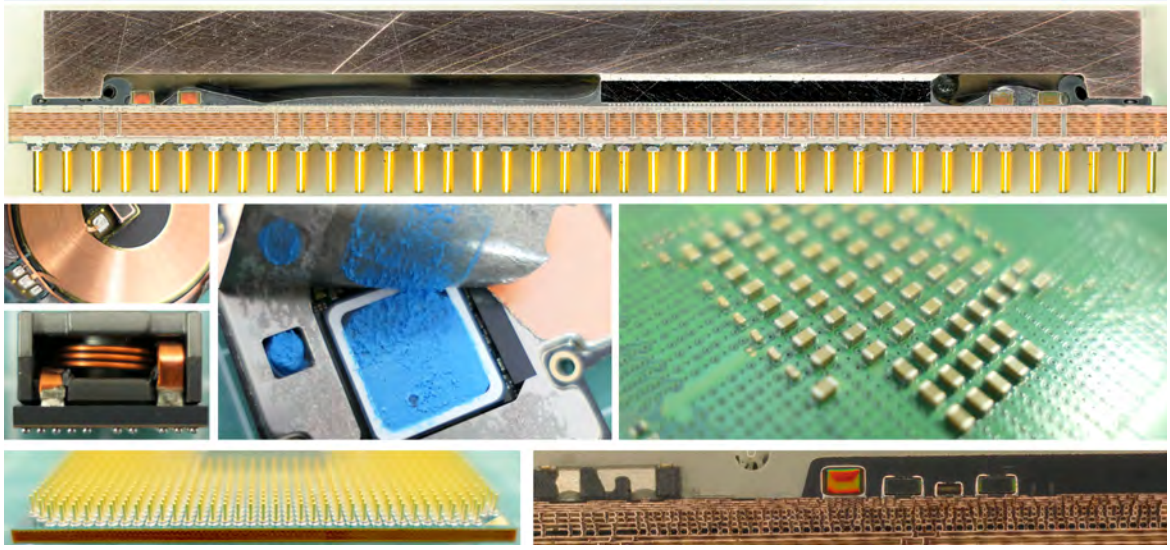
THE SEMICONDUCTOR AND PACKAGING REPORT

FOURTH QUARTER 2023



- STATE OF THE SEMICONDUCTOR AND PACKAGE BUSINESS : HIGHLIGHTS
- STATE OF THE SEMICONDUCTOR AND PACKAGE BUSINESS
  - Prismark's global economic and electronics forecast for 2023/2024F/2028F, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- 2023 SEMICONDUCTOR MARKET REVIEW AND 2024/2028 FORECASTS
  - Review of semiconductor market and package trends for 2023, revised 2024 forecast, and an outlook to 2028. Detailed unit and value forecasts by device type and package type, highlighting the increasing importance of advanced packaging to overall packaging value-add.
- INTEL'S AMBITION IN FOVEROS PACKAGING
  - Intel's introduction of its Core Ultra Meteor Lake processor using Foveros technology is an important milepost in the volume implementation of 2.5D packaging.
- SMARTPHONE AP PACKAGING UPDATE
  - Comparison of most recent APs introduced by Qualcomm and MediaTek
- GLOBAL WAFER CAPACITY AND WAFER PRODUCTION IN CHINA
  - Geopolitical concerns and supply chain resiliency has spawned a wave of global investments in semiconductor fabs. China has moved aggressively to expand its capacity even in the face of semiconductor manufacturing equipment export restrictions.
- UPDATES ON TAIWANESE NOTEBOOK ODMS
  - Updates on key notebook ODMs and their recent business performance and investment activities
- COMPANY NEWS: SEMICONDUCTOR AND WAFER FABRICATION
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- COMPANY NEWS: SEMICONDUCTOR PACKAGING
  - Recent developments in packaging at leading OSAT and captive assembly operations

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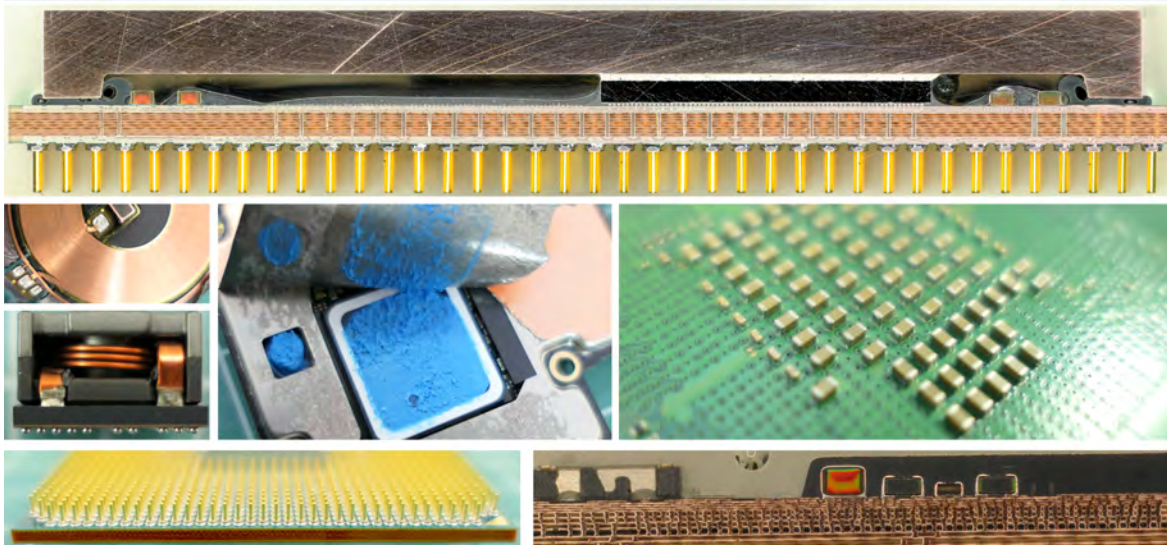
THE SEMICONDUCTOR AND PACKAGING REPORT

THIRD QUARTER 2023



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update, 2024 Preliminary Forecast, and 2027 Outlook
  - Review of semiconductor market and package trends for 2023, 2024 preliminary forecast, and an outlook to 2027
- IC Packaging Forecast Update
  - A review and forecast for the IC packaging market with an update on the advanced packaging market for mobile phone and server applications
- Updates on Handset Market and Chipset Supply in China
  - Updates on the handset market in China, including the chipset supply chain and local handset suppliers' company news
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations

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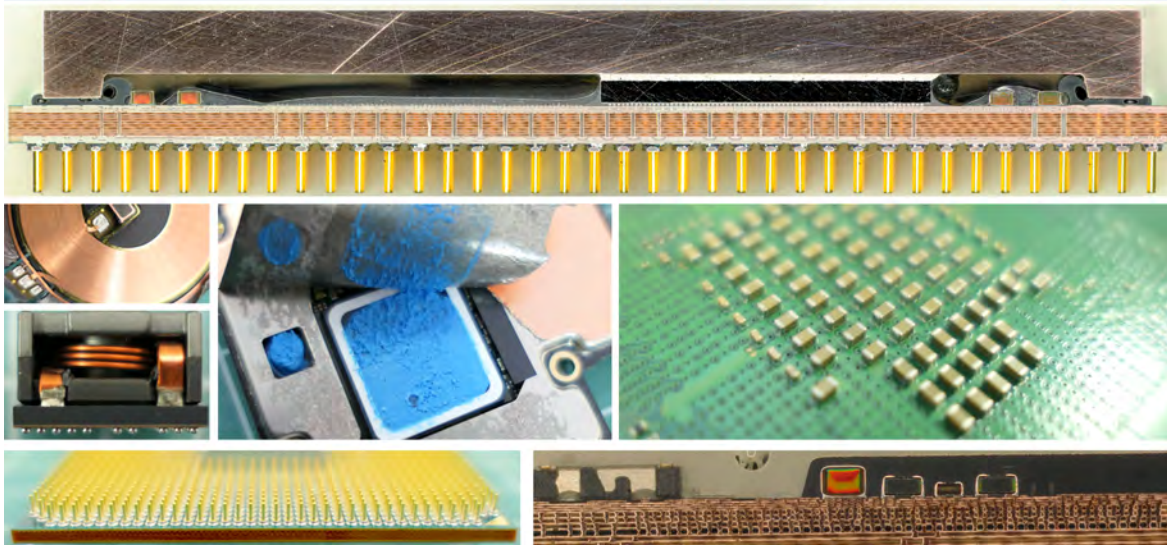
THE SEMICONDUCTOR AND PACKAGING REPORT

SECOND QUARTER 2023



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update and Revised 2027 Outlook
  - Review of semiconductor market and package trends for 2023 and an outlook to 2027
- Regional Split of Semiconductor Back-End Activity
  - A review and discussion on back-end activities by manufacturing site among the leading IDM and OSAT companies
- Updates on Handset Manufacturing Industry in Greater China
  - Updates on the handset manufacturing industry in Greater China with a focus on the changing ODM landscape
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations

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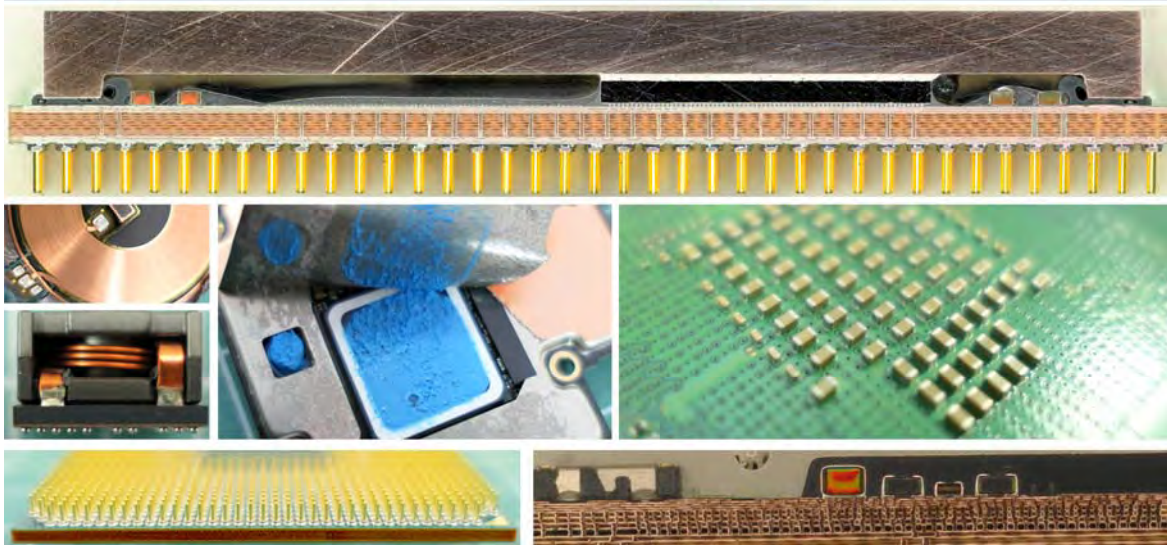
THE SEMICONDUCTOR AND PACKAGING REPORT

FIRST QUARTER 2023



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments, Prismark's global economic and electronics forecast for 2023, actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries
- Semiconductor and Packaging: 2023 Market Update and Revised 2027 Outlook
  - Review of semiconductor market and package trends for 2022, 2023, and an outlook to 2027
- The AI Boom: A Gold Rush Expansion in Advanced Packaging Demand
  - A review and discussion of the impact of the explosive growth in AI servers on advanced packaging. Are we in a bubble?
- Updates on China's Semiconductor Industry
  - Updates on China's semiconductor industry with a focus on the IC design and IC packaging and test segments
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings
- Company News: Semiconductor Packaging
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PRISMARK PARTNERS LLC

CONSULTANTS TO THE ELECTRONICS INDUSTRY
BUSINESS OPPORTUNITY FROM TECHNOLOGY AND
MARKET CHANGES

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